[SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICHWIRING PATTERNS ARE FORMED]

Abstract of Disclosure

The solder paste printing method of the present invention mounts a solder paste containing therein as a solder material a Sn-Zn system solder on a mask, and urges the solder paste to make rolling over the mask from one end thereof toward the opposite thereof by means of a squeegee to thereby fill the solder paste into apertures formed in the mask. At this time, by maintaining moisture contained in the atmosphere surrounding the solder paste at a value equal to or less than a predetermined value, as the solder paste is suppressed from causing an increase in the viscosity thereof due to the reaction with the moisture in the surrounding atmosphere during the solder paste printing process, the rolling ability of the solder paste during the printing process can be kept, and attachment of the solder paste to the squeegee can be prevented.

Figures